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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	48MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LCD, LVD, POR, PWM, WDT
Number of I/O	51
Program Memory Size	64KB (32K x 16)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	3.8K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 3.6V
Data Converters	A/D 12x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	80-TQFP
Supplier Device Package	80-TQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f86j72t-i-pt

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TABLE 1-2: PIC18F8XJ72 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTF is a bidirectional I/O port.
RF1/AN6/C2OUT/ SEG19	21			
RF1		I/O	ST	Digital I/O.
AN6		I	Analog	Analog Input 6.
C2OUT		O	—	Comparator 2 output.
SEG19		O	Analog	SEG19 output for LCD.
RF2/AN7/C1OUT/ SEG20	18			
RF2		I/O	ST	Digital I/O.
AN7		I	Analog	Analog Input 7.
C1OUT		O	—	Comparator 1 output.
SEG20		O	Analog	SEG20 output for LCD.
RF3/AN8/SEG21/ C2INB	17			
RF3		I/O	ST	Digital I/O.
AN8		I	Analog	Analog Input 8.
SEG21		O	Analog	SEG21 output for LCD.
C2INB		I	Analog	Comparator 2 Input B.
RF4/AN9/SEG22/ C2INA	16			
RF4		I/O	ST	Digital I/O.
AN9		I	Analog	Analog Input 9.
SEG22		O	Analog	SEG22 output for LCD
C2INA		I	Analog	Comparator 2 Input A.
RF5/AN10/CVREF/ SEG23/C1INB	15			
RF5		I/O	ST	Digital I/O.
AN10		I	Analog	Analog Input 10.
CVREF		O	Analog	Comparator reference voltage output.
SEG23		O	Analog	SEG23 output for LCD.
C1INB		I	Analog	Comparator 1 Input B.
RF6/AN11/SEG24/ C1INA	14			
RF6		I/O	ST	Digital I/O.
AN11		I	Analog	Analog Input 11.
SEG24		O	Analog	SEG24 output for LCD
C1INA		I	Analog	Comparator 1 Input A.
RF7/AN5/$\overline{SS}$/SEG25	13			
RF7		I/O	ST	Digital I/O.
AN5		O	Analog	Analog Input 5.
$\overline{SS}$		I	TTL	SPI slave select input.
SEG25		O	Analog	SEG25 output for LCD.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; Analog = Analog input; I^2C = I^2C/SMBus compatible input; OD = Open-Drain (no P diode to VDD); I = Input; O = Output; P = Power

Note 1: Default assignment for CCP2 when the CCP2MX Configuration bit is set.

2: Alternate assignment for CCP2 when the CCP2MX Configuration bit is cleared.

5.7 Reset State of Registers

Most registers are unaffected by a Reset. Their status is unknown on POR and unchanged by all other Resets. The other registers are forced to a “Reset state” depending on the type of Reset that occurred.

Most registers are not affected by a WDT wake-up, since this is viewed as the resumption of normal operation. Status bits from the RCON register, $\overline{RI}$, $\overline{TO}$, $\overline{PD}$, $\overline{POR}$ and $\overline{BOR}$, are set or cleared differently in different Reset situations, as indicated in Table 5-1. These bits are used in software to determine the nature of the Reset.

Table 5-2 describes the Reset states for all of the Special Function Registers. These are categorized by Power-on and Brown-out Resets, Master Clear and WDT Resets and WDT wake-ups.

TABLE 5-1: STATUS BITS, THEIR SIGNIFICANCE AND THE INITIALIZATION CONDITION FOR RCON REGISTER

Condition	Program Counter(1)	RCON Register					STKPTR Register	
		$\overline{RI}$	$\overline{TO}$	$\overline{PD}$	$\overline{POR}$	$\overline{BOR}$	STKFUL	STKUNF
Power-on Reset	0000h	1	1	1	0	0	0	0
RESET Instruction	0000h	0	u	u	u	u	u	u
Brown-out Reset	0000h	1	1	1	u	0	u	u
$\overline{MCLR}$ during power-managed Run modes	0000h	u	1	u	u	u	u	u
$\overline{MCLR}$ during power-managed Idle modes and Sleep mode	0000h	u	1	0	u	u	u	u
WDT time-out during full power or power-managed Run modes	0000h	u	0	u	u	u	u	u
$\overline{MCLR}$ during full power execution	0000h	u	u	u	u	u	u	u
Stack Full Reset (STVREN = 1)	0000h	u	u	u	u	u	1	u
Stack Underflow Reset (STVREN = 1)	0000h	u	u	u	u	u	u	1
Stack Underflow Error (not an actual Reset, STVREN = 0)	0000h	u	u	u	u	u	u	1
WDT time-out during power-managed Idle or Sleep modes	PC + 2	u	0	0	u	u	u	u
Interrupt exit from power-managed modes	PC + 2	u	u	0	u	u	u	u

Legend: u = unchanged

Note 1: When the wake-up is due to an interrupt and the GIEH or GIEL bit is set, the PC is loaded with the interrupt vector (0008h or 0018h).

9.1 INTCON Registers

The INTCON registers are readable and writable registers which contain various enable, priority and flag bits.

Note: Interrupt flag bits are set when an interrupt condition occurs regardless of the state of its corresponding enable bit or the global interrupt enable bit. User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt. This feature allows for software polling.

REGISTER 9-1: INTCON: INTERRUPT CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-x
GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **GIE/GIEH:** Global Interrupt Enable bit
When IPEN = 0:
1 = Enables all unmasked interrupts
0 = Disables all interrupts
When IPEN = 1:
1 = Enables all high-priority interrupts
0 = Disables all interrupts

bit 6 **PEIE/GIEL:** Peripheral Interrupt Enable bit
When IPEN = 0:
1 = Enables all unmasked peripheral interrupts
0 = Disables all peripheral interrupts
When IPEN = 1:
1 = Enables all low-priority peripheral interrupts
0 = Disables all low-priority peripheral interrupts

bit 5 **TMR0IE:** TMR0 Overflow Interrupt Enable bit
1 = Enables the TMR0 overflow interrupt
0 = Disables the TMR0 overflow interrupt

bit 4 **INT0IE:** INT0 External Interrupt Enable bit
1 = Enables the INT0 external interrupt
0 = Disables the INT0 external interrupt

bit 3 **RBIE:** RB Port Change Interrupt Enable bit
1 = Enables the RB port change interrupt
0 = Disables the RB port change interrupt

bit 2 **TMR0IF:** TMR0 Overflow Interrupt Flag bit
1 = TMR0 register has overflowed (must be cleared in software)
0 = TMR0 register did not overflow

bit 1 **INT0IF:** INT0 External Interrupt Flag bit
1 = The INT0 external interrupt occurred (must be cleared in software)
0 = The INT0 external interrupt did not occur

bit 0 **RBIF:** RB Port Change Interrupt Flag bit(1)
1 = At least one of the RB<7:4> pins changed state (must be cleared in software)
0 = None of the RB<7:4> pins have changed state

Note 1: A mismatch condition will continue to set this bit. Reading PORTB, then waiting one instruction cycle, will end the mismatch condition and allow the bit to be cleared.

TABLE 12-1: CAPACITOR SELECTION FOR THE TIMER1 OSCILLATOR(2,3,4)

Oscillator Type	Freq.	C1	C2
LP	32.768 kHz	27 pF(1)	27 pF(1)

Note 1: Microchip suggests these values as a starting point in validating the oscillator circuit.

2: Higher capacitance increases the stability of the oscillator but also increases the start-up time.

3: Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropriate values of external components.

4: Capacitor values are for design guidance only.

12.3.1 USING TIMER1 AS A CLOCK SOURCE

The Timer1 oscillator is also available as a clock source in power-managed modes. By setting the System Clock Select bits, SCS<1:0> (OSCCON<1:0>), to '01', the device switches to SEC_RUN mode. Both the CPU and peripherals are clocked from the Timer1 oscillator. If the IDLEN bit (OSCCON<7>) is cleared and a SLEEP instruction is executed, the device enters SEC_IDLE mode. Additional details are available in **Section 4.0 "Power-Managed Modes"**.

Whenever the Timer1 oscillator is providing the clock source, the Timer1 system clock status flag, T1RUN (T1CON<6>), is set. This can be used to determine the controller's current clocking mode. It can also indicate the clock source being currently used by the Fail-Safe Clock Monitor. If the Clock Monitor is enabled and the Timer1 oscillator fails while providing the clock, polling the T1RUN bit will indicate whether the clock is being provided by the Timer1 oscillator or another source.

15.6 Register Maps

Table 15-5, Table 15-6 and Table 15-7 summarize the registers associated with the RTCC module.

TABLE 15-5: RTCC CONTROL REGISTERS

File Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets on Page
RTCCFG	RTCEN	—	RTCWREN	RTCSYNC	HALFSEC	RTCOE	RTCPTR1	RTCPTR0	50
RTCCAL	CAL7	CAL6	CAL5	CAL4	CAL3	CAL2	CAL1	CAL0	50
PADCFG1	—	—	—	—	—	RTSECSEL1	RTSECSEL0	—	50
ALRMCFG	ALRMEN	CHIME	AMASK3	AMASK2	AMASK1	AMASK0	ALRMPTR1	ALRMPTR0	50
ALRMRPT	ARPT7	ARPT6	ARPT5	ARPT4	ARPT3	ARPT2	ARPT1	ARPT0	50

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal for 80-pin devices.

TABLE 15-6: RTCC VALUE REGISTERS

File Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets on Page
RTCVALH	RTCC Value High Register Window Based on RTCPTR<1:0>								50
RTCVALL	RTCC Value Low Register Window Based on RTCPTR<1:0>								50

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal for 80-pin devices.

TABLE 15-7: ALARM VALUE REGISTERS

File Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets on Page
ALRMVALH	Alarm Value High Register Window Based on ALRMPTR<1:0>								50
ALRMVALL	Alarm Value Low Register Window Based on ALRMPTR<1:0>								50

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal for 80-pin devices.

16.1 CCP Module Configuration

Each Capture/Compare/PWM module is associated with a control register (generically, CCPxCON) and a data register (CCPRx). The data register, in turn, is comprised of two 8-bit registers: CCPRxL (low byte) and CCPRxH (high byte). All registers are both readable and writable.

16.1.1 CCP MODULES AND TIMER RESOURCES

The CCP modules utilize timers, 1, 2 or 3, depending on the mode selected. Timer1 and Timer3 are available to modules in Capture or Compare modes, while Timer2 is available for modules in PWM mode.

TABLE 16-1: CCP MODE – TIMER RESOURCE

CCP Mode	Timer Resource
Capture	Timer1 or Timer3
Compare	Timer1 or Timer3
PWM	Timer2

The assignment of a particular timer to a module is determined by the Timer to CCP enable bits in the T3CON register (Register 14-1). Both modules may be active at any given time and may share the same timer resource if they are configured to operate in the same mode (Capture/Compare or PWM) at the same time. The interactions between the two modules are summarized in Table 16-2.

Depending on the configuration selected, up to four timers may be active at once, with modules in the same configuration (Capture/Compare or PWM) sharing timer resources. The possible configurations are shown in Figure 16-1.

16.1.2 OPEN-DRAIN OUTPUT OPTION

When operating in Output mode (i.e., in Compare or PWM modes), the drivers for the CCPx pins can be optionally configured as open-drain outputs. This feature allows the voltage level on the pin to be pulled to a higher level through an external pull-up resistor and allows the output to communicate with external circuits without the need for additional level shifters.

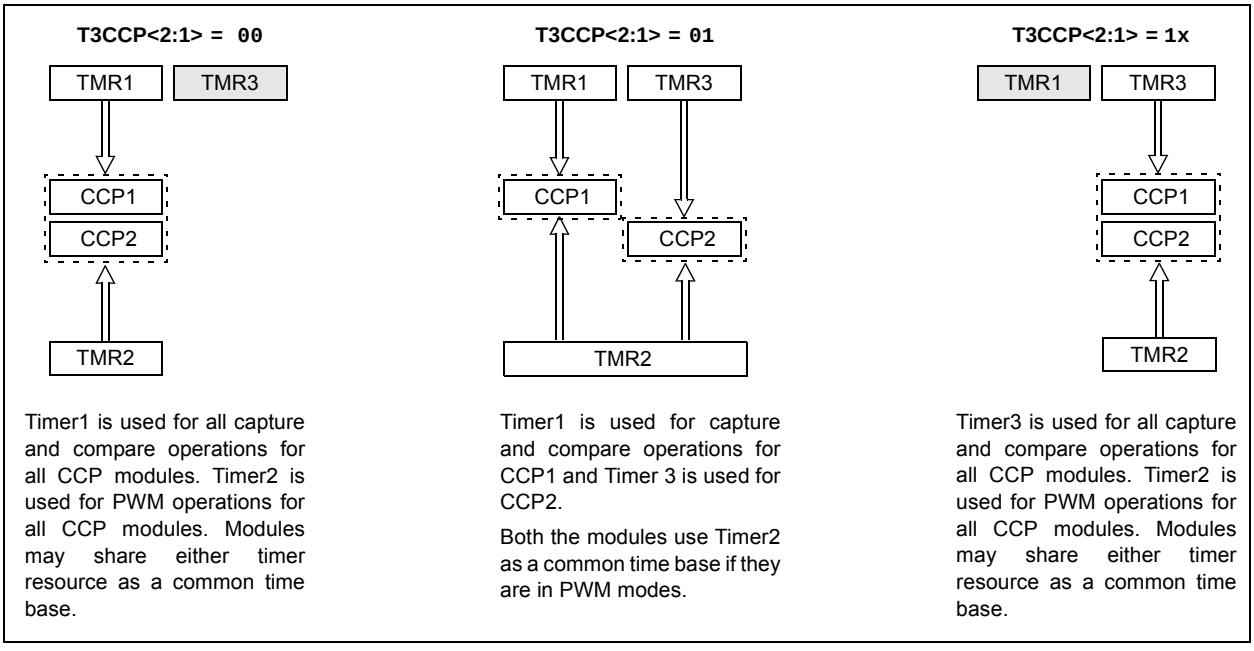
The open-drain output option is controlled by the CCP2OD and CCP1OD bits (TRISG<6:5>). Setting the appropriate bit configures the pin for the corresponding module for open-drain operation.

16.1.3 CCP2 PIN ASSIGNMENT

The pin assignment for CCP2 (capture input, compare and PWM output) can change, based on device configuration. The CCP2MX Configuration bit determines which pin CCP2 is multiplexed to. By default, it is assigned to RC1 (CCP2MX = 1). If the Configuration bit is cleared, CCP2 is multiplexed with RE7.

Changing the pin assignment of CCP2 does not automatically change any requirements for configuring the port pin. Users must always verify that the appropriate TRIS register is configured correctly for CCP2 operation, regardless of where it is located.

FIGURE 16-1: CCP AND TIMER INTERCONNECT CONFIGURATIONS



16.4 PWM Mode

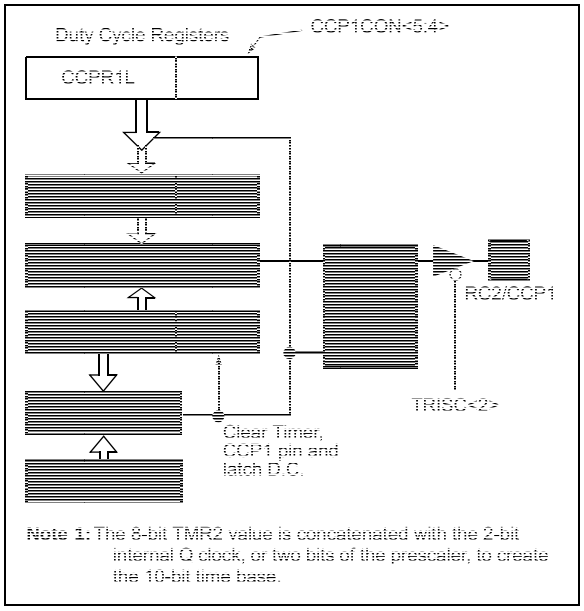
In Pulse-Width Modulation (PWM) mode, the CCP2 pin produces up to a 10-bit resolution PWM output. Since the CCP2 pin is multiplexed with a PORTC or PORTE data latch, the appropriate TRIS bit must be cleared to make the CCP2 pin an output.

Note:	Clearing the CCP2CON register will force the RC1 or RE7 output latch (depending on device configuration) to the default low level. This is not the PORTC or PORTE I/O data latch.

Figure 16-4 shows a simplified block diagram of the CCP1 module in PWM mode.

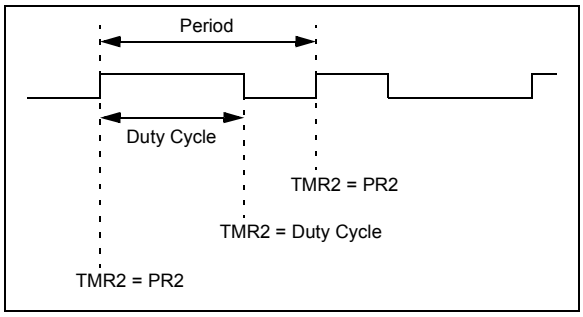
For a step-by-step procedure on how to set up the CCP module for PWM operation, see **Section 16.4.3 "Setup for PWM Operation"**.

FIGURE 16-4: SIMPLIFIED PWM BLOCK DIAGRAM



A PWM output (Figure 16-5) has a time base (period) and a time that the output stays high (duty cycle). The frequency of the PWM is the inverse of the period (1/period).

FIGURE 16-5: PWM OUTPUT



16.4.1 PWM PERIOD

The PWM period is specified by writing to the PR2 register. The PWM period can be calculated using the following formula:

EQUATION 16-1:

$$\text{PWM Period} = (PR2) + 1] \cdot 4 \cdot T_{OSC} \cdot (\text{TMR2 Prescale Value})$$

PWM frequency is defined as 1/[PWM period].

When TMR2 is equal to PR2, the following three events occur on the next increment cycle:

- TMR2 is cleared
- The CCP2 pin is set (exception: if PWM duty cycle = 0%, the CCP2 pin will not be set)
- The PWM duty cycle is latched from CCPR2L into CCPR2H

Note:	The Timer2 postscalers (see **Section 13.0 "Timer2 Module"**) are not used in the determination of the PWM frequency. The postscaler could be used to have a servo update rate at a different frequency than the PWM output.

FIGURE 17-6: TYPE-A/TYPE-B WAVEFORMS IN STATIC DRIVE

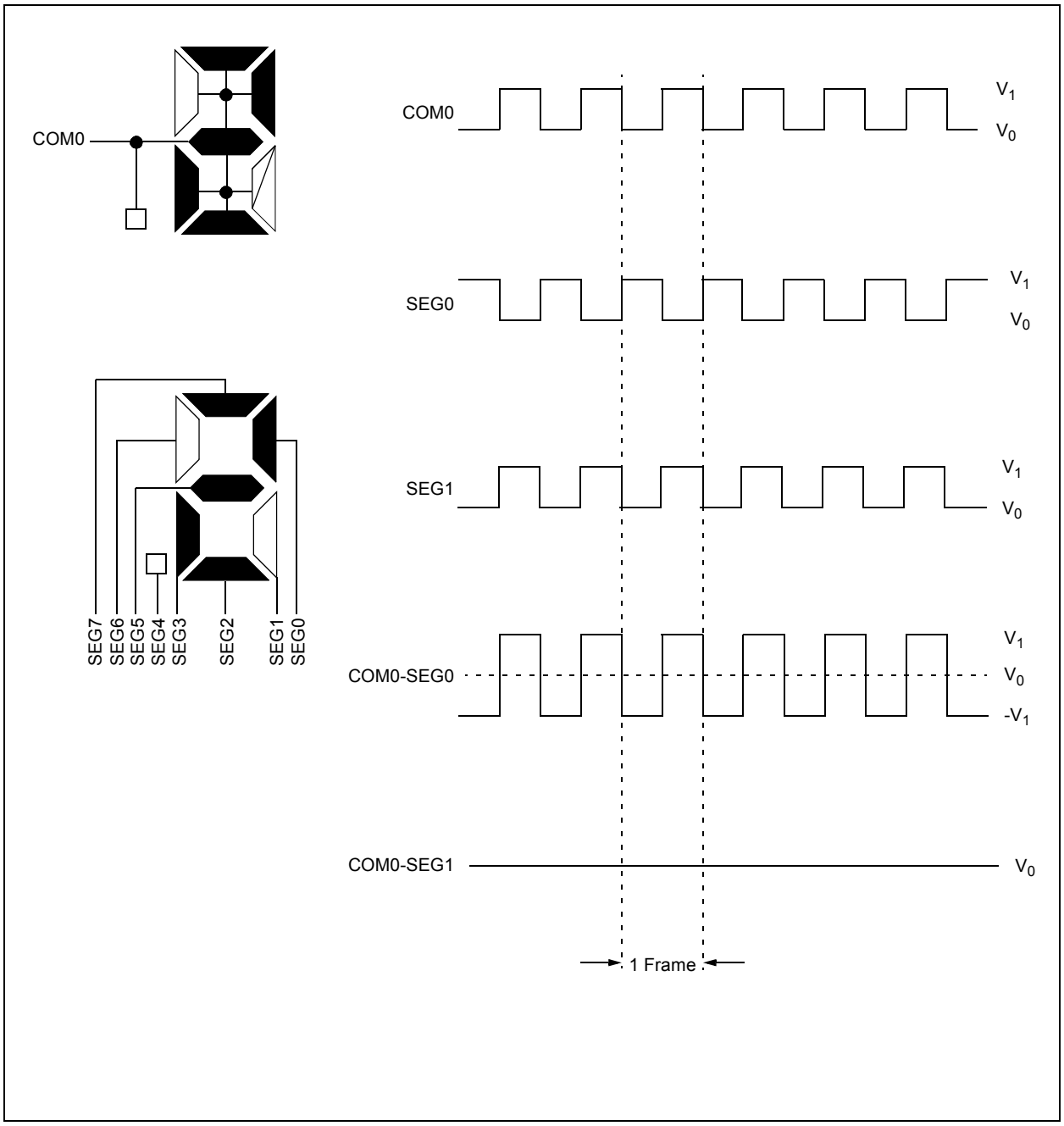
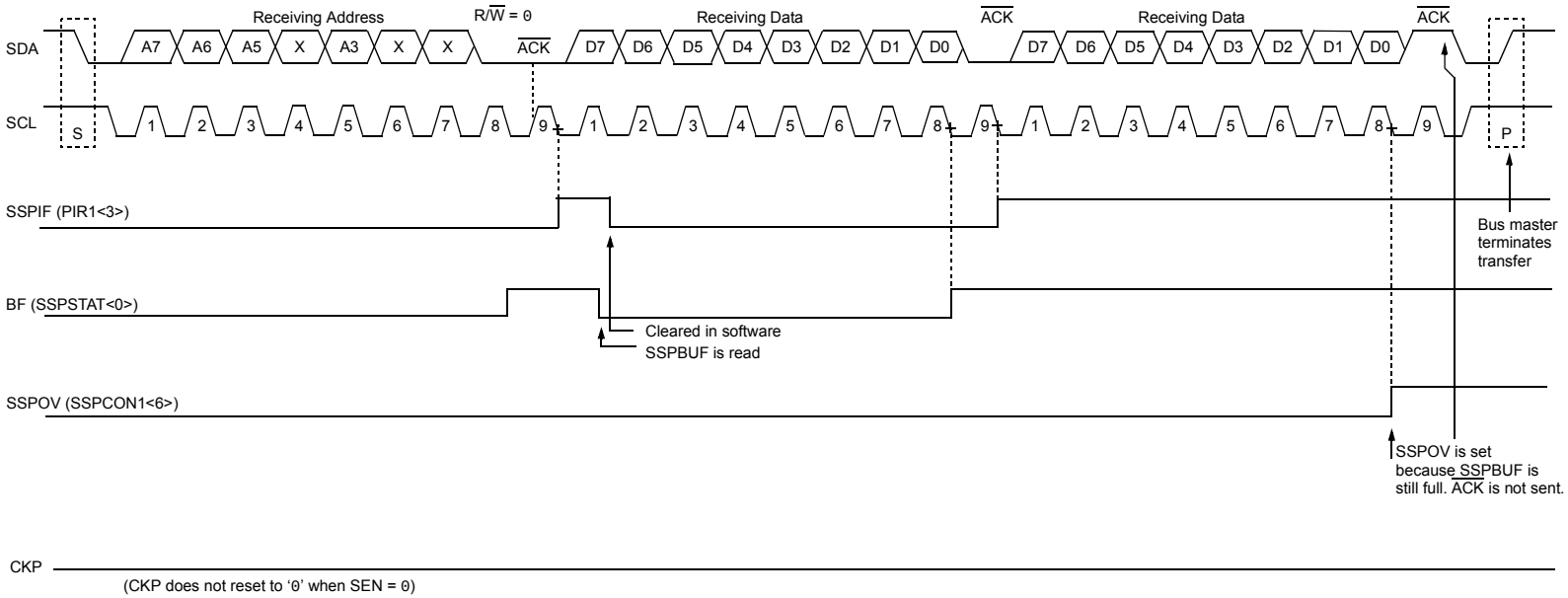


FIGURE 18-9: I²C SLAVE MODE TIMING WITH SEN = 0 AND ADMSK<5:1> = 01011 (RECEPTION, 7-BIT ADDRESSING)



Note 1: x = Don't care (i.e., address bit can be either a '1' or a '0').

2: In this example, an address equal to A7.A6.A5.X.A3.X.X will be Acknowledged and cause an interrupt.

18.4.8 I²C MASTER MODE START CONDITION TIMING

To initiate a Start condition, the user sets the Start Enable bit, SEN (SSPCON2<0>). If the SDA and SCL pins are sampled high, the Baud Rate Generator is reloaded with the contents of SSPADD<6:0> and starts its count. If SCL and SDA are both sampled high when the Baud Rate Generator times out (TBRG), the SDA pin is driven low. The action of the SDA being driven low while SCL is high is the Start condition and causes the S bit (SSPSTAT<3>) to be set. Following this, the Baud Rate Generator is reloaded with the contents of SSPADD<6:0> and resumes its count. When the Baud Rate Generator times out (TBRG), the SEN bit (SSPCON2<0>) will automatically be cleared by hardware. The Baud Rate Generator is suspended, leaving the SDA line held low and the Start condition is complete.

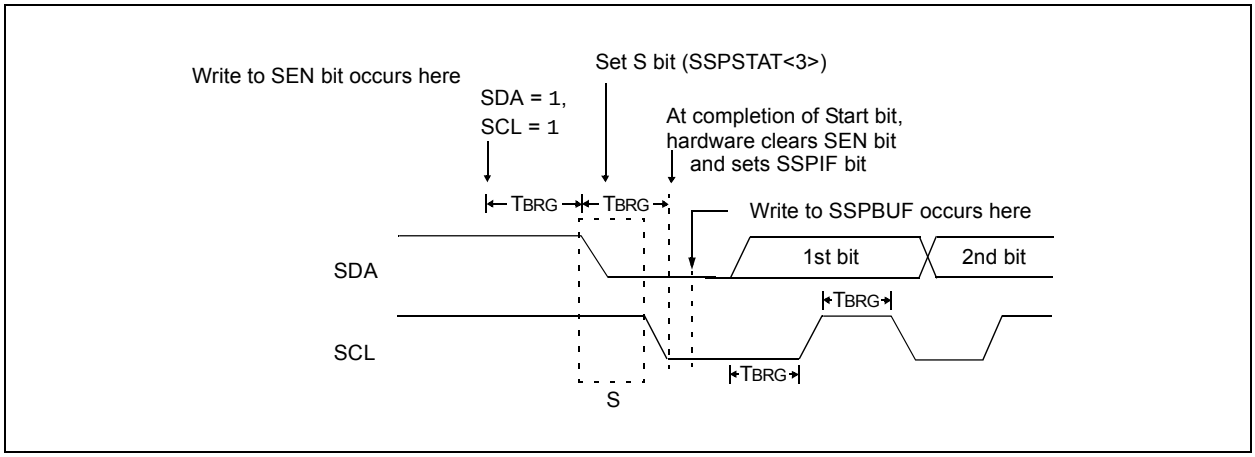
Note:	If, at the beginning of the Start condition, the SDA and SCL pins are already sampled low, or if during the Start condition, the SCL line is sampled low before the SDA line is driven low, a bus collision occurs. The Bus Collision Interrupt Flag, BCLIF, is set, the Start condition is aborted and the I²C module is reset into its Idle state.

18.4.8.1 WCOL Status Flag

If the user writes the SSPBUF when a Start sequence is in progress, the WCOL is set and the contents of the buffer are unchanged (the write does not occur).

Note:	Because queuing of events is not allowed, writing to the lower five bits of SSPCON2 is disabled until the Start condition is complete.

FIGURE 18-21: FIRST START BIT TIMING



21.1 A/D Acquisition Requirements

For the A/D Converter to meet its specified accuracy, the Charge Holding Capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The analog input model is shown in Figure 21-2. The source impedance (RS) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor, CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD). The source impedance affects the offset voltage at the analog input (due to pin leakage current). **The maximum recommended impedance for analog sources is 2.5 kΩ**. After the analog input channel is selected (changed), the channel must be sampled for at least the minimum acquisition time before starting a conversion.

Note:	When the conversion is started, the holding capacitor is disconnected from the input pin.

To calculate the minimum acquisition time, Equation 21-1 may be used. This equation assumes that 1/2 LSb error is used (1,024 steps for the A/D). The 1/2 LSb error is the maximum error allowed for the A/D to meet its specified resolution.

Equation 21-3 shows the calculation of the minimum required acquisition time, TACQ. This calculation is based on the following application system assumptions:

CHOLD	=	25 pF
Rs	=	2.5 kΩ
Conversion Error	≤	1/2 LSb
VDD	=	3V → Rss = 2 kΩ
Temperature	=	85°C (system max.)

EQUATION 21-1: ACQUISITION TIME

$$T_{ACQ} = \text{Amplifier Settling Time} + \text{Holding Capacitor Charging Time} + \text{Temperature Coefficient}$$
$$= T_{AMP} + T_C + T_{COFF}$$

EQUATION 21-2: A/D MINIMUM CHARGING TIME

$$V_{HOLD} = (V_{REF} - (V_{REF}/2048)) \cdot (1 - e^{(-T_C/C_{HOLD}(R_{IC} + R_{SS} + R_S))})$$
or
$$T_C = -(C_{HOLD})(R_{IC} + R_{SS} + R_S)\ \ln(1/2048)$$

EQUATION 21-3: CALCULATING THE MINIMUM REQUIRED ACQUISITION TIME

$$T_{ACQ} = T_{AMP} + T_C + T_{COFF}$$
$$T_{AMP} = 0.2\ \mu s$$
$$T_{COFF} = (Temp - 25°C)(0.02\ \mu s/°C)$$
$$(85°C - 25°C)(0.02\ \mu s/°C)$$
$$1.2\ \mu s$$

Temperature coefficient is only required for temperatures > 25°C. Below 25°C, T_{COFF} = 0 ms.

$$T_C = -(C_{HOLD})(R_{IC} + R_{SS} + R_S)\ \ln(1/2048)\ \mu s$$
$$-(25\ pF)\ (1\ k\Omega + 2\ k\Omega + 2.5\ k\Omega)\ \ln(0.0004883)\ \mu s$$
$$1.05\ \mu s$$
$$T_{ACQ} = 0.2\ \mu s + 1\ \mu s + 1.2\ \mu s$$
$$2.4\ \mu s$$

25.0 CHARGE TIME MEASUREMENT UNIT (CTMU)

The Charge Time Measurement Unit (CTMU) is a flexible analog module that provides accurate differential time measurement between pulse sources, as well as asynchronous pulse generation. By working with other on-chip analog modules, the CTMU can be used to precisely measure time, measure capacitance, measure relative changes in capacitance or generate output pulses with a specific time delay. The CTMU is ideal for interfacing with capacitive-based sensors.

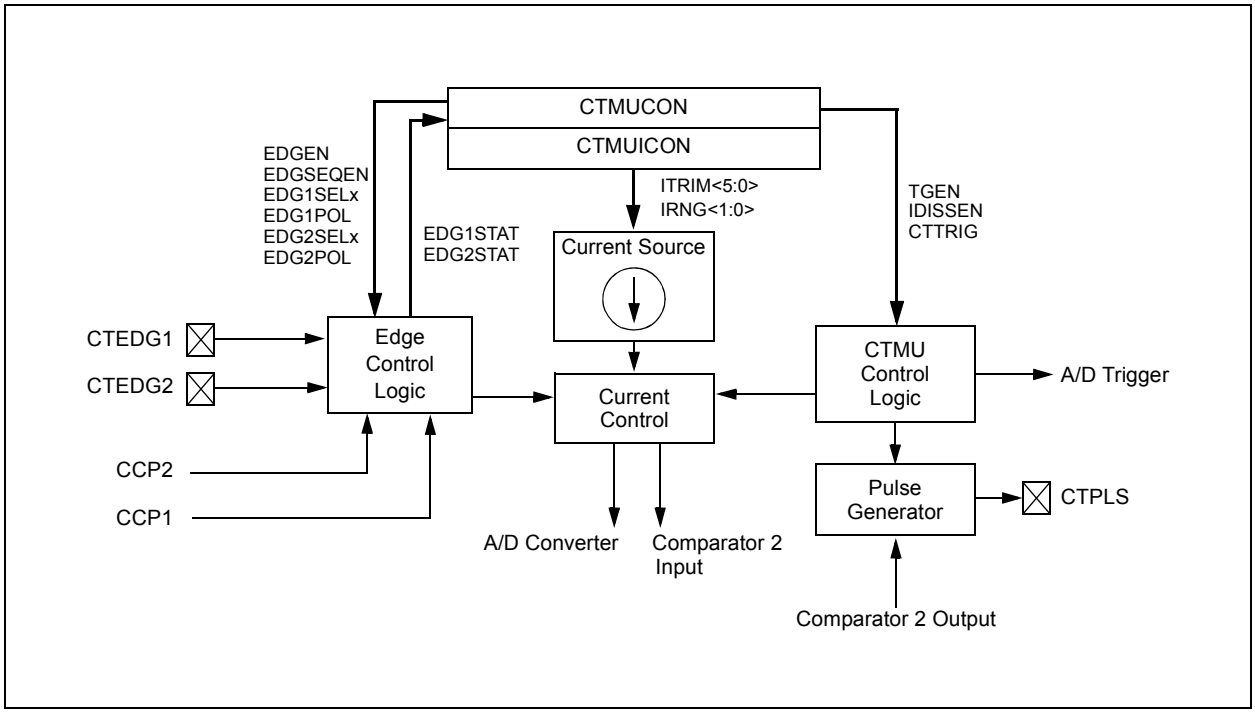
The module includes the following key features:

- Up to 13 channels available for capacitive or time measurement input
- On-chip precision current source
- Four-edge input trigger sources
- Polarity control for each edge source
- Control of edge sequence
- Control of response to edges
- Time measurement resolution of 1 nanosecond
- High-precision time measurement
- Time delay of external or internal signal asynchronous to system clock
- Accurate current source suitable for capacitive measurement

The CTMU works in conjunction with the A/D Converter to provide up to 13 channels for time or charge measurement, depending on the specific device and the number of A/D channels available. When configured for time delay, the CTMU is connected to one of the analog comparators. The level-sensitive input edge sources can be selected from four sources: two external inputs or CCP1/CCP2 Special Event Triggers.

Figure 25-1 provides a block diagram of the CTMU.

FIGURE 25-1: CTMU BLOCK DIAGRAM



EXAMPLE 25-3: CAPACITANCE CALIBRATION ROUTINE

```
#include "p18cxxx.h"

#define COUNT 25                        //@ 8MHz INTFRC = 62.5 us.
#define ETIME COUNT*2.5                 //time in uS
#define DELAY for(i=0;i<COUNT;i++)
#define ADSCALE 1023                    //for unsigned conversion 10 sig bits
#define ADREF 3.3                       //Vdd connected to A/D Vr+
#define RCAL .027                       //R value is 4200000 (4.2M)
                                        //scaled so that result is in
                                        //1/100th of uA

int main(void)
{
    int i;
    int j = 0;                          //index for loop
    unsigned int Vread = 0;
    float CTMUISrc, CTMUCap, Vavg, VTot, Vcal;

//assume CTMU and A/D have been setup correctly
//see Example 25-1 for CTMU & A/D setup
setup();

CTMUCONHbits.CTMUEN = 1;                //Enable the CTMU
    for(j=0;j<10;j++)
    {
        CTMUCONHbits.IDISSEN = 1;       //drain charge on the circuit
        DELAY;                          //wait 125us
        CTMUCONHbits.IDISSEN = 0;       //end drain of circuit

        CTMUCONLbits.EDG1STAT = 1;      //Begin charging the circuit
                                        //using CTMU current source
        DELAY;                          //wait for 125us
        CTMUCONLbits.EDG1STAT = 0;      //Stop charging circuit

        PIR1bits.ADIF = 0;              //make sure A/D Int not set
        ADCON0bits.GO=1;                //and begin A/D conv.
        while(!PIR1bits.ADIF);          //Wait for A/D convert complete


        Vread = ADRES;                  //Get the value from the A/D
        PIR1bits.ADIF = 0;              //Clear A/D Interrupt Flag
        VTot += Vread;                  //Add the reading to the total
    }

    Vavg = (float)(VTot/10.000);        //Average of 10 readings
    Vcal = (float)(Vavg/ADSCALE*ADREF);
    CTMUISrc = Vcal/RCAL;               //CTMUISrc is in 1/100ths of uA
    CTMUCap = (CTMUISrc*ETIME/Vcal)/100;
}
```

BCF **Bit Clear f**

Syntax: BCF f, b {,a}

Operands: $0 \le f \le 255$
$0 \le b \le 7$
$a \in [0,1]$

Operation: $0 \rightarrow f<b>$

Status Affected: None

Encoding:

1001	bbba	ffff	ffff

Description: Bit 'b' in register 'f' is cleared.

If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.

If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See **Section 27.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write register 'f'

Example: `BCF FLAG_REG, 7, 0`

Before Instruction
FLAG_REG = C7h
After Instruction
FLAG_REG = 47h

BN **Branch if Negative**

Syntax: BN n

Operands: $-128 \le n \le 127$

Operation: if Negative bit is '1',
$(PC) + 2 + 2n \rightarrow PC$

Status Affected: None

Encoding:

1110	0110	nnnn	nnnn

Description: If the Negative bit is '1', then the program will branch.

The 2's complement number '2n' is added to the PC. Since the PC will have incremented to fetch the next instruction, the new address will be PC + 2 + 2n. This instruction is then a 2-cycle instruction.

Words: 1

Cycles: 1(2)

Q Cycle Activity:
If Jump:

Q1	Q2	Q3	Q4
Decode	Read literal 'n'	Process Data	Write to PC
No operation	No operation	No operation	No operation

If No Jump:

Q1	Q2	Q3	Q4
Decode	Read literal 'n'	Process Data	No operation

Example:
```
HERE    BN   Jump
```

Before Instruction
PC = address (HERE)
After Instruction
If Negative = 1;
PC = address (Jump)
If Negative = 0;
PC = address (HERE + 2)

BNOV **Branch if Not Overflow**

Syntax: BNOV n

Operands: -128 ≤ n ≤ 127

Operation: if Overflow bit is '0',
(PC) + 2 + 2n → PC

Status Affected: None

Encoding:

1110	0101	nnnn	nnnn

Description: If the Overflow bit is '0', then the program will branch.

The 2's complement number '2n' is added to the PC. Since the PC will have incremented to fetch the next instruction, the new address will be PC + 2 + 2n. This instruction is then a 2-cycle instruction.

Words: 1

Cycles: 1(2)

Q Cycle Activity:

If Jump:

Q1	Q2	Q3	Q4
Decode	Read literal 'n'	Process Data	Write to PC
No operation	No operation	No operation	No operation

If No Jump:

Q1	Q2	Q3	Q4
Decode	Read literal 'n'	Process Data	No operation

Example: HERE BNOV Jump

Before Instruction
PC = address (HERE)
After Instruction
If Overflow = 0;
PC = address (Jump)
If Overflow = 1;
PC = address (HERE + 2)

BNZ **Branch if Not Zero**

Syntax: BNZ n

Operands: -128 ≤ n ≤ 127

Operation: if Zero bit is '0',
(PC) + 2 + 2n → PC

Status Affected: None

Encoding:

1110	0001	nnnn	nnnn

Description: If the Zero bit is '0', then the program will branch.

The 2's complement number '2n' is added to the PC. Since the PC will have incremented to fetch the next instruction, the new address will be PC + 2 + 2n. This instruction is then a 2-cycle instruction.

Words: 1

Cycles: 1(2)

Q Cycle Activity:

If Jump:

Q1	Q2	Q3	Q4
Decode	Read literal 'n'	Process Data	Write to PC
No operation	No operation	No operation	No operation

If No Jump:

Q1	Q2	Q3	Q4
Decode	Read literal 'n'	Process Data	No operation

Example: HERE BNZ Jump

Before Instruction
PC = address (HERE)
After Instruction
If Zero = 0;
PC = address (Jump)
If Zero = 1;
PC = address (HERE + 2)

POP **Pop Top of Return Stack**

Syntax: POP

Operands: None

Operation: (TOS) → bit bucket

Status Affected: None

Encoding:

0000	0000	0000	0110

Description: The TOS value is pulled off the return stack and is discarded. The TOS value then becomes the previous value that was pushed onto the return stack. This instruction is provided to enable the user to properly manage the return stack to incorporate a software stack.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	No operation	POP TOS value	No operation

Example:
```
POP
GOTO    NEW
```
Before Instruction
TOS = 0031A2h
Stack (1 level down) = 014332h

After Instruction
TOS = 014332h
PC = NEW

PUSH **Push Top of Return Stack**

Syntax: PUSH

Operands: None

Operation: (PC + 2) → TOS

Status Affected: None

Encoding:

0000	0000	0000	0101

Description: The PC + 2 is pushed onto the top of the return stack. The previous TOS value is pushed down on the stack. This instruction allows implementing a software stack by modifying TOS and then pushing it onto the return stack.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	PUSH PC + 2 onto return stack	No operation	No operation

Example:
```
PUSH
```
Before Instruction
TOS = 345Ah
PC = 0124h

After Instruction
PC = 0126h
TOS = 0126h
Stack (1 level down) = 345Ah

MOVSS **Move Indexed to Indexed**

Syntax: MOVSS [z_s], [z_d]

Operands: $0 \le z_s \le 127$
$0 \le z_d \le 127$

Operation: ((FSR2) + z_s) → ((FSR2) + z_d)

Status Affected: None

Encoding:

1st word (source)	1110	1011	1zzz	$zzzz_s$
2nd word (dest.)	1111	xxxx	xzzz	$zzzz_d$

Description: The contents of the source register are moved to the destination register. The addresses of the source and destination registers are determined by adding the 7-bit literal offsets, 'z_s' or 'z_d', respectively, to the value of FSR2. Both registers can be located anywhere in the 4096-byte data memory space (000h to FFFh).

The MOVSS instruction cannot use the PCL, TOSU, TOSH or TOSL as the destination register.

If the resultant source address points to an Indirect Addressing register, the value returned will be 00h. If the resultant destination address points to an Indirect Addressing register, the instruction will execute as a NOP.

Words: 2

Cycles: 2

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Determine source addr	Determine source addr	Read source reg
Decode	Determine dest addr	Determine dest addr	Write to dest reg

Example: MOVSS [05h], [06h]

Before Instruction
FSR2 = 80h
Contents of 85h = 33h
Contents of 86h = 11h
After Instruction
FSR2 = 80h
Contents of 85h = 33h
Contents of 86h = 33h

PUSHL **Store Literal at FSR2, Decrement FSR2**

Syntax: PUSHL k

Operands: $0 \le k \le 255$

Operation: k → (FSR2),
FSR2 – 1 → FSR2

Status Affected: None

Encoding:

1111	1010	kkkk	kkkk

Description: The 8-bit literal 'k' is written to the data memory address specified by FSR2. FSR2 is decremented by 1 after the operation.

This instruction allows users to push values onto a software stack.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read 'k'	Process data	Write to destination

Example: PUSHL 08h

Before Instruction
FSR2H:FSR2L = 01ECh
Memory (01ECh) = 00h

After Instruction
FSR2H:FSR2L = 01EBh
Memory (01ECh) = 08h

29.1 DC Characteristics: Power-Down and Supply Current PIC18F87J72 Family (Industrial)

PIC18F87J72 Family (Industrial)		Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial				
Param. No.	**Device**	**Typ.**	**Max.**	**Units**	**Conditions**	
	Power-Down Current (I_{PD})(1)					
	All devices	0.5	1.4	µA	-40°C	V_{DD} = 2.0V(4) (**Sleep** mode)
		0.1	1.4	µA	+25°C	
		0.8	6	µA	+60°C	
		5.5	10.2	µA	+85°C	
	All devices	0.5	1.5	µA	-40°C	V_{DD} = 2.5V(4) (**Sleep** mode)
		0.1	1.5	µA	+25°C	
		1	8	µA	+60°C	
		6.8	12.6	µA	+85°C	
	All devices	2.9	7	µA	-40°C	V_{DD} = 3.3V(5) (**Sleep** mode)
		3.6	7	µA	+25°C	
		4.1	10	µA	+60°C	
		9.6	19	µA	+85°C	

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to V_{DD} or V_{SS} and all features that add delta current disabled (such as WDT, Timer1 oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.

The test conditions for all I_{DD} measurements in active operation mode are:

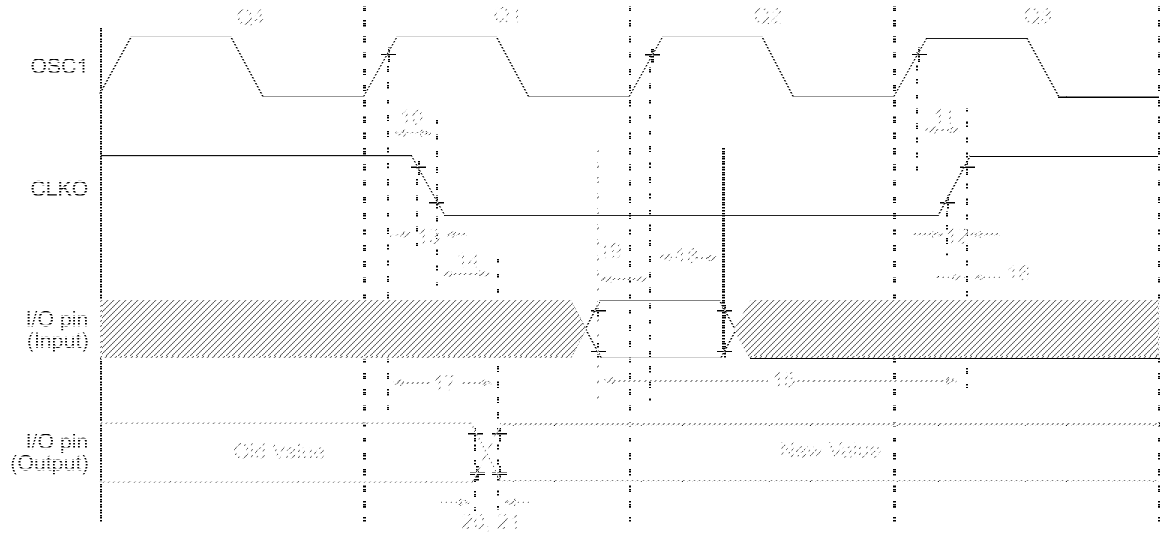
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to V_{DD};
$\overline{MCLR}$ = V_{DD}; WDT enabled/disabled as specified.

3: Standard, low-cost 32 kHz crystals have an operating temperature range of -10°C to +70°C. Extended temperature crystals are available at a much higher cost.

4: Voltage regulator is disabled (ENVREG = 0, tied to V_{SS}).

5: Voltage regulator is enabled (ENVREG = 1, tied to V_{DD}, REGSLP = 1).

FIGURE 29-5: CLKO AND I/O TIMING



Note: Refer to Figure 29-3 for load conditions.

TABLE 29-1: CLKO AND I/O TIMING REQUIREMENTS

Param. No.	Symbol	Characteristic	Min.	Typ.	Max.	Units	Conditions
10	TOSH2CKL	OSC1 ↑ to CLKO ↓	—	75	200	ns	**(Note 1)**
11	TOSH2CKH	OSC1 ↑ to CLKO ↑	—	75	200	ns	**(Note 1)**
12	TCKR	CLKO Rise Time	—	15	30	ns	**(Note 1)**
13	TCKF	CLKO Fall Time	—	15	30	ns	**(Note 1)**
14	TCKL2IOV	CLKO ↓ to Port Out Valid	—	—	0.5 TCY + 20	ns	
15	TIOV2CKH	Port In Valid before CLKO ↑	0.25 TCY + 25	—	—	ns	
16	TCKH2IOI	Port In Hold after CLKO ↑	0	—	—	ns	
17	TOSH2IOV	OSC1 ↑ (Q1 cycle) to Port Out Valid	—	50	150	ns	
18	TOSH2IOI	OSC1 ↑ (Q2 cycle) to Port Input Invalid (I/O in hold time)	100	—	—	ns	
19	TIOV2OSH	Port Input Valid to OSC1 ↑ (I/O in setup time)	0	—	—	ns	
20	TIOR	Port Output Rise Time	—	—	6	ns	
21	TIOF	Port Output Fall Time	—	—	5	ns	
22†	TINP	INTx Pin High or Low Time	TCY	—	—	ns	
23†	TRBP	RB<7:4> Change INTx High or Low Time	TCY	—	—	ns	

† These parameters are asynchronous events not related to any internal clock edges.

Note 1: Measurements are taken in EC mode, where CLKO output is 4 x TOSC.